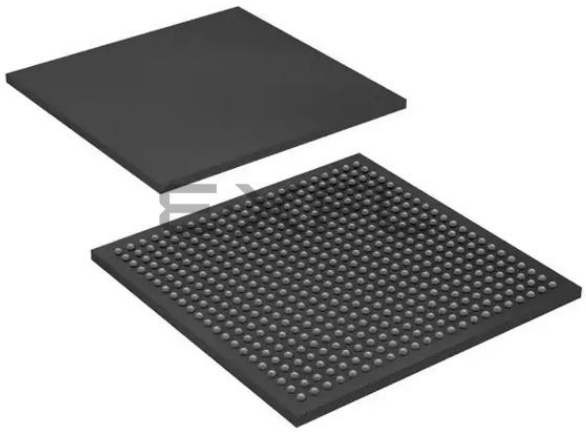

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Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Active
Number of LABs/CLBs	1172
Number of Logic Elements/Cells	18752
Total RAM Bits	239616
Number of I/O	315
Number of Gates	-
Voltage - Supply	1.15V ~ 1.25V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 100°C (TJ)
Package / Case	484-BGA
Supplier Device Package	484-FBGA (23x23)
Purchase URL	https://www.e-xfl.com/product-detail/intel/ep2c20f484i8n

Chapter 10. Selectable I/O Standards in Cyclone II Devices
Revised: *February 2008*
Part number: *CII51010-2.4*

Chapter 11. High-Speed Differential Interfaces in Cyclone II Devices
Revised: *February 2007*
Part number: *CII51011-2.2*

Chapter 12. Embedded Multipliers in Cyclone II Devices
Revised: *February 2007*
Part number: *CII51012-1.2*

Chapter 13. Configuring Cyclone II Devices
Revised: *February 2007*
Part number: *CII51013-3.1*

Chapter 14. IEEE 1149.1 (JTAG) Boundary-Scan Testing for Cyclone II Devices
Revised: *February 2007*
Part number: *CII51014-2.1*

Chapter 15. Package Information for Cyclone II Devices
Revised: *February 2007*
Part number: *CII51015-2.3*

1. Introduction

CII51001-3.2

Introduction

Following the immensely successful first-generation Cyclone® device family, Altera® Cyclone II FPGAs extend the low-cost FPGA density range to 68,416 logic elements (LEs) and provide up to 622 usable I/O pins and up to 1.1 Mbits of embedded memory. Cyclone II FPGAs are manufactured on 300-mm wafers using TSMC's 90-nm low-k dielectric process to ensure rapid availability and low cost. By minimizing silicon area, Cyclone II devices can support complex digital systems on a single chip at a cost that rivals that of ASICs. Unlike other FPGA vendors who compromise power consumption and performance for low-cost, Altera's latest generation of low-cost FPGAs—Cyclone II FPGAs, offer 60% higher performance and half the power consumption of competing 90-nm FPGAs. The low cost and optimized feature set of Cyclone II FPGAs make them ideal solutions for a wide array of automotive, consumer, communications, video processing, test and measurement, and other end-market solutions. Reference designs, system diagrams, and IP, found at www.altera.com, are available to help you rapidly develop complete end-market solutions using Cyclone II FPGAs.

Low-Cost Embedded Processing Solutions

Cyclone II devices support the Nios II embedded processor which allows you to implement custom-fit embedded processing solutions. Cyclone II devices can also expand the peripheral set, memory, I/O, or performance of embedded processors. Single or multiple Nios II embedded processors can be designed into a Cyclone II device to provide additional co-processing power or even replace existing embedded processors in your system. Using Cyclone II and Nios II together allow for low-cost, high-performance embedded processing solutions, which allow you to extend your product's life cycle and improve time to market over standard product solutions.

Low-Cost DSP Solutions

Use Cyclone II FPGAs alone or as DSP co-processors to improve price-to-performance ratios for digital signal processing (DSP) applications. You can implement high-performance yet low-cost DSP systems with the following Cyclone II features and design support:

- Up to 150 18 × 18 multipliers
- Up to 1.1 Mbit of on-chip embedded memory
- High-speed interfaces to external memory

protocols. Visit the Altera IPMegaStore at www.altera.com to download IP MegaCore functions.

- Nios II Embedded Processor support

The Cyclone II family offers devices with the Fast-On feature, which offers a faster power-on-reset (POR) time. Devices that support the Fast-On feature are designated with an "A" in the device ordering code. For example, EP2C5A, EP2C8A, EP2C15A, and EP2C20A. The EP2C5A is only available in the automotive speed grade. The EP2C8A and EP2C20A are only available in the industrial speed grade. The EP2C15A is only available with the Fast-On feature and is available in both commercial and industrial grades. The Cyclone II "A" devices are identical in feature set and functionality to the non-A devices except for support of the faster POR time.

Cyclone II A devices are offered in automotive speed grade. For more information, refer to the Cyclone II section in the *Automotive-Grade Device Handbook*.

For more information on POR time specifications for Cyclone II A and non-A devices, refer to the *Hot Socketing & Power-On Reset* chapter in the *Cyclone II Device Handbook*.

Table 1–1 lists the Cyclone II device family features. Table 1–2 lists the Cyclone II device package offerings and maximum user I/O pins.

Table 1–1. Cyclone II FPGA Family Features (Part 1 of 2)

Feature	EP2C5 *(2)*	EP2C8 *(2)*	EP2C15 *(1)*	EP2C20 *(2)*	EP2C35	EP2C50	EP2C70
LEs	4,608	8,256	14,448	18,752	33,216	50,528	68,416
M4K RAM blocks (4 Kbits plus 512 parity bits	26	36	52	52	105	129	250
Total RAM bits	119,808	165,888	239,616	239,616	483,840	594,432	1,152,000
Embedded multipliers *(3)*	13	18	26	26	35	86	150
PLLs	2	2	4	4	4	4	4

Table 5–30. EP2C35 Row Pins Global Clock Timing Parameters

Parameter	Fast Corner		–6 Speed Grade	–7 Speed Grade	–8 Speed Grade	Unit
	Industrial	Commercial				
t_{CIN}	1.410	1.476	2.514	2.724	2.986	ns
t_{COUT}	1.412	1.478	2.530	2.737	2.994	ns
t_{PLLCIN}	–0.117	–0.127	0.134	0.162	0.241	ns
$t_{PLLCOUT}$	–0.115	–0.125	0.15	0.175	0.249	ns

EP2C50 Clock Timing Parameters

Tables 5–31 and 5–32 show the clock timing parameters for EP2C50 devices.

Table 5–31. EP2C50 Column Pins Global Clock Timing Parameters

Parameter	Fast Corner		–6 Speed Grade	–7 Speed Grade	–8 Speed Grade	Unit
	Industrial	Commercial				
t_{CIN}	1.575	1.651	2.759	2.940	3.174	ns
t_{COUT}	1.589	1.666	2.793	2.972	3.203	ns
t_{PLLCIN}	–0.149	–0.158	0.113	0.075	0.089	ns
$t_{PLLCOUT}$	–0.135	–0.143	0.147	0.107	0.118	ns

Table 5–32. EP2C50 Row Pins Global Clock Timing Parameters

Parameter	Fast Corner		–6 Speed Grade	–7 Speed Grade	–8 Speed Grade	Unit
	Industrial	Commercial				
t_{CIN}	1.463	1.533	2.624	2.791	3.010	ns
t_{COUT}	1.465	1.535	2.640	2.804	3.018	ns
t_{PLLCIN}	–0.261	–0.276	–0.022	–0.074	–0.075	ns
$t_{PLLCOUT}$	–0.259	–0.274	–0.006	–0.061	–0.067	ns

I/O Delays

Refer to Tables 5–39 through 5–43 for I/O delays.

Table 5–39. I/O Delay Parameters

Symbol	Parameter
t_{DIP}	Delay from I/O datain to output pad
t_{OP}	Delay from I/O output register to output pad
t_{PCOUT}	Delay from input pad to I/O dataout to core
t_{PI}	Delay from input pad to I/O input register

Table 5–40. Cyclone II I/O Input Delay for Column Pins (Part 1 of 3)

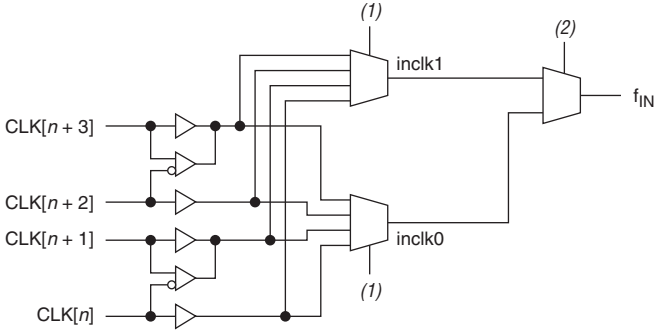
I/O Standard	Parameter	Fast Corner		–6 Speed Grade	–7 Speed Grade (1)	–7 Speed Grade (2)	–8 Speed Grade	Unit
		Industrial/ Automotive	Commer -cial					
LVTTL	t_{PI}	581	609	1222	1228	1282	1282	ps
	t_{PCOUT}	367	385	760	783	854	854	ps
2.5V	t_{PI}	624	654	1192	1238	1283	1283	ps
	t_{PCOUT}	410	430	730	793	855	855	ps
1.8V	t_{PI}	725	760	1372	1428	1484	1484	ps
	t_{PCOUT}	511	536	910	983	1056	1056	ps
1.5V	t_{PI}	790	828	1439	1497	1556	1556	ps
	t_{PCOUT}	576	604	977	1052	1128	1128	ps
LVCMOS	t_{PI}	581	609	1222	1228	1282	1282	ps
	t_{PCOUT}	367	385	760	783	854	854	ps
SSTL_2_CLASS_I	t_{PI}	533	558	990	1015	1040	1040	ps
	t_{PCOUT}	319	334	528	570	612	612	ps
SSTL_2_CLASS_II	t_{PI}	533	558	990	1015	1040	1040	ps
	t_{PCOUT}	319	334	528	570	612	612	ps
SSTL_18_CLASS_I	t_{PI}	577	605	1027	1035	1045	1045	ps
	t_{PCOUT}	363	381	565	590	617	617	ps
SSTL_18_CLASS_II	t_{PI}	577	605	1027	1035	1045	1045	ps
	t_{PCOUT}	363	381	565	590	617	617	ps

Manual Clock Switchover

The Cyclone II PLLs support manual switchover of the reference clock through internal logic. This enables you to switch between two reference input clocks. Use this feature for a dual clock domain application such as in a system that turns on the redundant clock if the primary clock stops running.

Figure 7–10 shows how the PLL input clock (f_{IN}) is generated from one of four possible clock sources. The first stage multiplexing consists of two dedicated multiplexers that generate two single-ended or two differential clocks from four dedicated clock pins. These clock signals are then multiplexed to generate f_{IN} by using another dedicated 2-to-1 multiplexer. The first stage multiplexers are controlled by configuration bit settings in the configuration file generated by the Quartus II software, while the second stage multiplexer is either controlled by the configuration bit settings or logic array signal to allow the f_{IN} to be controlled dynamically. This allows the implementation of a manual clock switchover circuit where the PLL reference clock can be switched during user mode for applications that requires clock redundancy.

Figure 7–10. Cyclone II PLL Input Clock Generation



Notes to Figure 7–10:

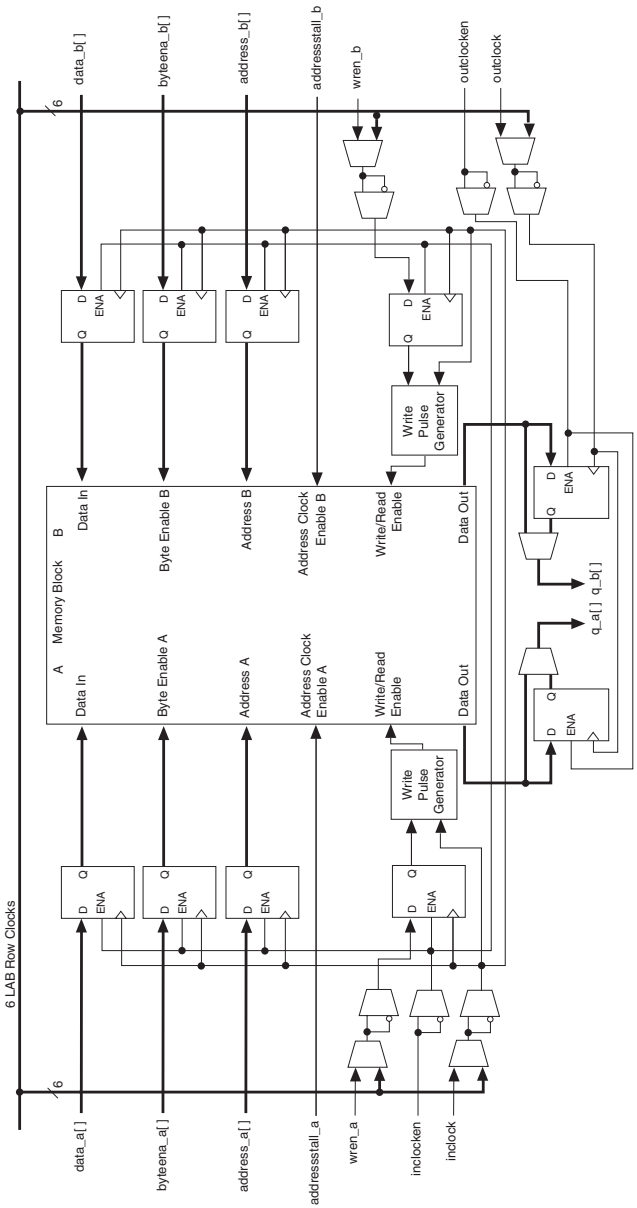
(1) This select line is set through the configuration file.

(2) This select line can either be set through the configuration file or it can be dynamically set in user mode when using the manual switchover feature.

Table 7–8. Global Clock Network Connections (Part 2 of 3)

Global Clock Network Clock Sources	Global Clock Networks															
	All Cyclone II Devices								EP2C15 through EP2C70 Devices Only							
	0	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15
PLL4_c0													✓	✓		✓
PLL4_c1													✓		✓	✓
PLL4_c2														✓	✓	
DPCLK0 *(1)*	✓															
DPCLK1 *(1)*		✓														
DPCLK10 *(1)*, *(2)* CDPCLK0 or CDPCLK7 *(3)*			✓													
DPCLK2 *(1)*, *(2)* CDPCLK1 or CDPCLK2 *(3)*				✓												
DPCLK7 *(1)*					✓											
DPCLK6 *(1)*						✓										
DPCLK8 *(1)*, *(2)* CDPCLK5 or CDPCLK6 *(3)*							✓									
DPCLK4 *(1)*, *(2)* CDPCLK4 or CDPCLK3 *(3)*								✓								
DPCLK8 *(1)*									✓							
DPCLK11 *(1)*										✓						
DPCLK9 *(1)*											✓					
DPCLK10 *(1)*												✓				
DPCLK5 *(1)*													✓			
DPCLK2 *(1)*														✓		
DPCLK4 *(1)*															✓	

Figure 8–14. Cyclone II Input/Output Clock Mode in True Dual-Port Mode *Note (1)*



Note to Figure 8–14:

(1) Violating the setup or hold time on the memory block address registers could corrupt memory contents. This applies to both read and write operations.

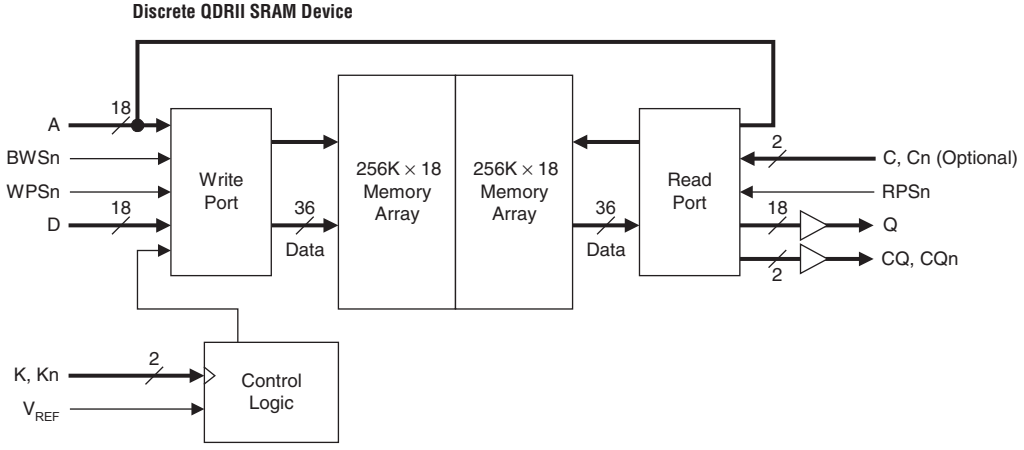
QDRII SRAM

QDRII SRAM is the second generation of QDR SRAM devices. QDRII SRAM devices, which can transfer four words per clock cycle, fulfill the requirements facing next-generation communications system designers. QDRII SRAM devices provide concurrent reads and writes, zero latency, increased data throughput, and allow simultaneous access to the same address location.

Interface Pins

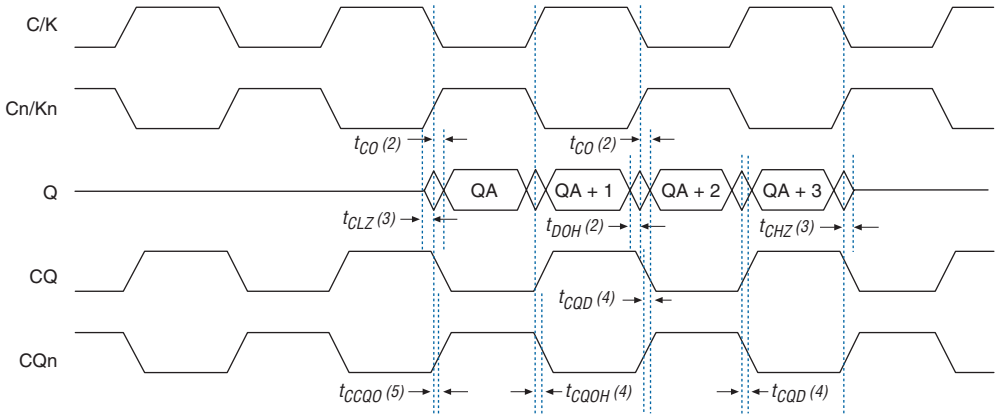
QDRII SRAM devices use two separate, unidirectional data ports for read and write operations, enabling four times the data transfer compared to single data rate devices. QDRII SRAM devices use common control and address lines for read and write operations. Figure 9–3 shows the block diagram for QDRII SRAM burst-of-two architecture.

Figure 9–3. QDRII SRAM Block Diagram for Burst-of-Two Architecture



QDRII SRAM burst-of-two devices sample the read address on the rising edge of the clock and the write address on the falling edge of the clock. QDRII SRAM burst-of-four devices sample both read and write addresses on the clock's rising edge. Connect the memory device's Q ports (read data) to the Cyclone II DQ pins. You can use any of the Cyclone II device's user I/O pins in the top and bottom I/O banks for the D ports (write data), commands, and addresses. For maximum performance, Altera recommends connecting the D ports (write data) to the Cyclone II DQ pins, because the DQ pins are pre-assigned to ensure minimal skew.

Figure 9–5. Data & Clock Relationship During a QDRII SRAM Report



Notes to Figure 9–5:

(1) The timing parameter nomenclature is based on the Cypress QDRII SRAM data sheet for CY7C1313V18.
(2) t_{CO} is the data clock-to-out time and t_{DOH} is the data output hold time between burst.
(3) t_{CLZ} and t_{CHZ} are bus turn-on and turn-off times, respectively.
(4) t_{CQD} is the skew between CQn and data edges.
(5) t_{CCQO} and t_{CQOH} are skew measurements between the C or C# clocks (or the K or K# clocks in single-clock mode) and the CQ or CQn clocks.

When writing to QDRII SRAM devices, the write clock generates the data while the K clock is 90° shifted from the write clock, creating a center-aligned arrangement.

- Cyclone II FPGA (EP2C15 or larger)
- Altera PCI Express Compiler ×1 MegaCore® function
- External PCI Express transceiver/PHY

2.5-V LVTTL (EIA/JEDEC Standard EIA/JESD8-5)

The 2.5-V I/O standard is used for 2.5-V LVTTL applications. This standard defines the DC interface parameters for high-speed, low-voltage, non-terminated digital circuits driving or being driven by other 2.5-V devices.

The 2.5-V standard does not require input reference voltages or board terminations. Cyclone II devices support input and output levels for 2.5-V LVTTL.

2.5-V LVCMOS (EIA/JEDEC Standard EIA/JESD8-5)

The 2.5-V I/O standard is used for 2.5-V LVCMOS applications. This standard defines the DC interface parameters for high-speed, low-voltage, non-terminated digital circuits driving or being driven by other 2.5-V parts.

The 2.5-V standard does not require input reference voltages or board terminations. Cyclone II devices support input and output levels for 2.5-V LVCMOS.

SSTL-2 Class I and II (EIA/JEDEC Standard JESD8-9A)

The SSTL-2 I/O standard is a 2.5-V memory bus standard used for applications such as high-speed double data rate (DDR) SDRAM interfaces. This standard defines the input and output specifications for devices that operate in the SSTL-2 logic switching range of 0.0 to 2.5 V. This standard improves operations in conditions where a bus must be isolated from large stubs. The SSTL-2 standard specifies an input voltage range of $-0.3\ V \leq V_I \leq V_{CCIO} + 0.3\ V$. SSTL-2 requires a V_{REF} value of 1.25 V and a V_{TT} value of 1.25 V connected to the termination resistors (refer to Figures 10–1 and 10–2).

Table 11–5 defines the parameters of the timing diagram shown in Figure 11–16. Figure 11–17 shows the Cyclone II high-speed I/O timing budget.

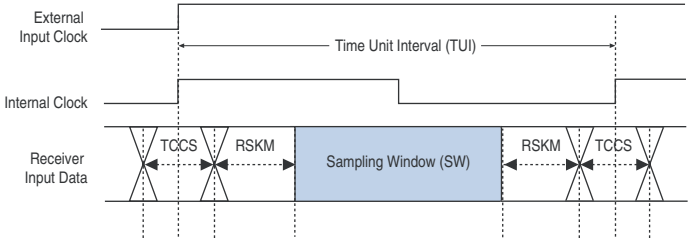
Table 11–5. High-Speed I/O Timing Definitions

Parameter	Symbol	Description
Transmitter channel-to-channel skew *(1)*	TCCS	The timing difference between the fastest and slowest output edges, including t_{CO} variation and clock skew. The clock is included in the TCCS measurement.
Sampling window	SW	The period of time during which the data must be valid in order for you to capture it correctly. The setup and hold times determine the ideal strobe position within the sampling window. $T_{SW} = T_{SU} + T_{hd}$ + PLL jitter.
Receiver input skew margin	RSKM	RSKM is defined by the total margin left after accounting for the sampling window and TCCS. The RSKM equation is: RSKM = (TUI – SW – TCCS) / 2.
Input jitter tolerance (peak-to-peak)		Allowed input jitter on the input clock to the PLL that is tolerable while maintaining PLL lock.
Output jitter (peak-to-peak)		Peak-to-peak output jitter from the PLL.

Note to Table 11–5:

(1) The TCCS specification applies to the entire bank of LVDS as long as the SERDES logic are placed within the LAB adjacent to the output pins.

Figure 11–16. High-Speed I/O Timing Diagram



See the *Cyclone II Memory Blocks* chapter in Volume 1 of the ***Cyclone II Device Handbook*** for more information on Cyclone II M4K memory blocks.

Refer to *AN 306: Techniques for Implementing Multipliers in FPGA Devices* for more information on soft multipliers.

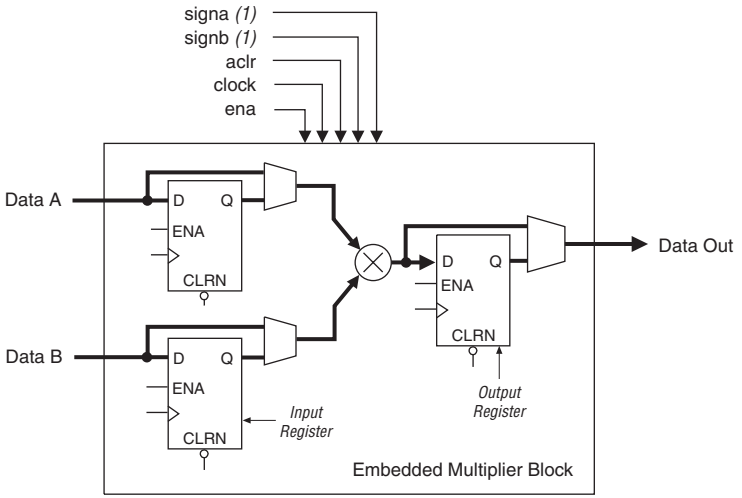
Architecture

Each embedded multiplier consists of the following elements:

- Multiplier stage
- Input and output registers
- Input and output interfaces

Figure 12–2 shows the multiplier block architecture.

Figure 12–2. Multiplier Block Architecture



Note to Figure 12–2:

(1) If necessary, you can send these signals through one register to match the data signal path.

Input Registers

You can send each multiplier input signal into an input register or directly into the multiplier in 9- or 18-bit sections depending on the operational mode of the multiplier. You can send each multiplier input signal through a register independently of each other (e.g., you can send the multiplier's

13. Configuring Cyclone II Devices

CII51013-3.1

Introduction

Cyclone® II devices use SRAM cells to store configuration data. Since SRAM memory is volatile, configuration data must be downloaded to Cyclone II devices each time the device powers up. You can use the active serial (AS) configuration scheme, which can operate at a DCLK frequency up to 40 MHz, to configure Cyclone II devices. You can also use the passive serial (PS) and Joint Test Action Group (JTAG)-based configuration schemes to configure Cyclone II devices. Additionally, Cyclone II devices can receive a compressed configuration bitstream and decompress this data on-the-fly, reducing storage requirements and configuration time.

This chapter explains the Cyclone II configuration features and describes how to configure Cyclone II devices using the supported configuration schemes. This chapter also includes configuration pin descriptions and the Cyclone II configuration file format.

For more information on setting device configuration options or creating configuration files, see the *Software Settings* chapter in the *Configuration Handbook*.

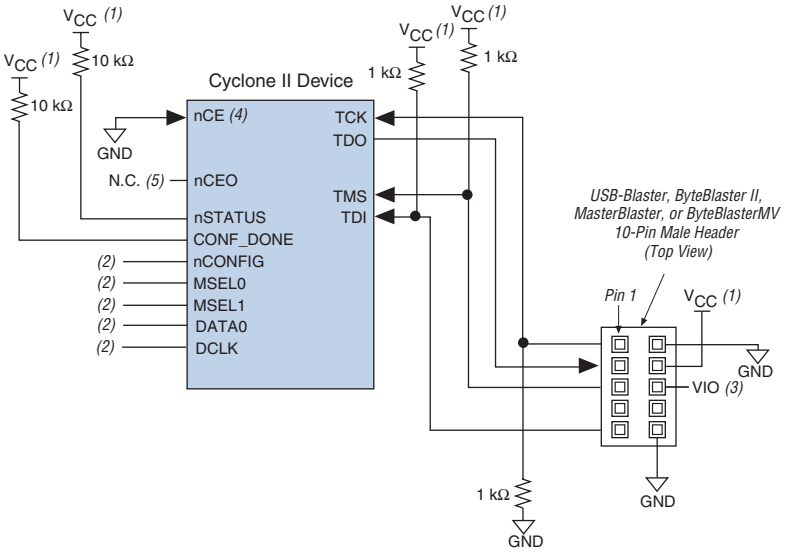
Cyclone II Configuration Overview

You can use the AS, PS, and JTAG configuration schemes to configure Cyclone II devices. You can select which configuration scheme to use by driving the Cyclone II device MSEL pins either high or low as shown in Table 13–1. The MSEL pins are powered by the V_{CCIO} power supply of the bank they reside in. The MSEL[1..0] pins have 9-kΩ internal pull-down resistors that are always active. During power-on reset (POR) and reconfiguration, the MSEL pins have to be at LVTTL V_{IL} or V_{IH} levels to be considered a logic low or logic high, respectively. Therefore, to avoid any problems with detecting an incorrect configuration scheme, you should connect the MSEL[] pins to the V_{CCIO} of the I/O bank they reside in and GND without any pull-up or pull-down resistors. The MSEL[] pins should not be driven by a microprocessor or another device.

Single Device JTAG Configuration

During JTAG configuration, you can use the USB-Blaster, MasterBlaster, ByteBlaster II, or ByteBlasterMV download cable to download data to the device. Configuring Cyclone II devices through a cable is similar to programming devices in system. Figure 13–22 shows JTAG configuration of a single Cyclone II device using a download cable.

Figure 13–22. JTAG Configuration of a Single Device Using a Download Cable



Notes to Figure 13–22:

(1) The pull-up resistor should be connected to the same supply voltage as the USB-Blaster, MasterBlaster (VIO pin), ByteBlaster II, or ByteBlasterMV cable.

(2) Connect the nCONFIG and MSEL[1..0] pins to support a non-JTAG configuration scheme. If only JTAG configuration is used, connect the nCONFIG pin to V_{CC}, and the MSEL[1..0] pins to ground. In addition, pull DCLK and DATA0 to either high or low, whichever is convenient on your board.

(3) Pin 6 of the header is a V_{IO} reference voltage for the MasterBlaster output driver. V_{IO} should match the device's V_{CCIO}. Refer to the *MasterBlaster Serial/USB Communications Cable Data Sheet* for this value. In the ByteBlasterMV, this pin is a no connect. In the USB-Blaster and ByteBlaster II, this pin is connected to nCE when it is used for AS programming, otherwise it is a no connect.

(4) nCE must be connected to GND or driven low for successful JTAG configuration.

(5) The nCEO pin can be left unconnected or used as a user I/O pin when it does not feed other device's nCE pin.

To configure a single device in a JTAG chain, the programming software places all other devices in BYPASS mode. In BYPASS mode, Cyclone II devices pass programming data from the TDI pin to the TDO pin through a single bypass register without being affected internally. This scheme

frequency (up to 40 MHz), which reduces your configuration time. In addition, Cyclone II devices can receive a compressed configuration bitstream and decompress this data on-the-fly in the AS or PS configuration scheme, which further reduces storage requirements and configuration time.

Table 15–4 provides θ_{JA} (junction-to-ambient thermal resistance) values, θ_{JC} (junction-to-case thermal resistance) values, θ_{JB} (junction-to-board thermal resistance) values for Cyclone II devices on a typical board.

Table 15–4. Thermal Resistance of Cyclone II Devices for Typical Board

Device	Pin Count	Package	θ_{JA} (°C/W) Still Air	θ_{JA} (°C/W) 100 ft./min.	θ_{JA} (°C/W) 200 ft./min.	θ_{JA} (°C/W) 400 ft./min.	θ_{JC} (°C/W)	θ_{JB} (°C/W)
EP2C5	256	FineLine BGA	30.2	25.8	22.9	20.6	8.7	14.8
EP2C8	256	FineLine BGA	27.9	23.2	20.5	18.4	7.1	12.3
EP2C15	256	FineLine BGA	24.7	20.1	17.5	15.3	5.5	9.1
	484	FineLine BGA	20.5	16.2	13.9	12.2	4.2	7.2
EP2C20	256	FineLine BGA	24.7	20.1	17.5	15.3	5.5	9.1
	484	FineLine BGA	20.5	16.2	13.9	12.2	4.2	7.2
EP2C35	484	FineLine BGA	18.8	14.5	12.3	10.6	3.3	5.7
	484	Ultra FineLine BGA	20	15.5	13.2	11.3	5	5.3
	672	FineLine BGA	17.4	13.3	11.3	9.8	3.1	5.5
EP2C50	484	FineLine BGA	17.7	13.5	11.4	9.8	2.8	4.5
	484	FineLine BGA	18.1	13.8	11.7	10.1	2.8	4.6
	484	Ultra FineLine BGA	19	14.6	12.3	10.6	4.4	4.4
	484	Ultra FineLine BGA	19.4	15	12.7	10.9	4.4	4.6
	672	FineLine BGA	16.5	12.4	10.5	9	2.6	4.6
EP2C70	672	FineLine BGA	15.7	11.7	9.8	8.3	2.2	3.8
	672	FineLine BGA	15.9	11.9	9.9	8.4	2.2	3.9
	896	FineLine BGA	14.6	10.7	8.9	7.6	2.1	3.7

Package Outlines

The package outlines on the following pages are listed in order of ascending pin count.

144-Pin Plastic Thin Quad Flat Pack (TQFP) – Wirebond

- All dimensions and tolerances conform to ASME Y14.5M – 1994.
- Controlling dimension is in millimeters.
- Pin 1 may be indicated by an ID dot, or a special feature, in its proximity on package surface.

484-Pin Ultra FineLine BGA – Wirebond

- All dimensions and tolerances conform to ASME Y14.5M – 1994.
- Controlling dimension is in millimeters.
- Pin A1 may be indicated by an ID dot, or a special feature, in its proximity on package surface.

Tables 15–15 and 15–16 show the package information and package outline figure references, respectively, for the 484-pin Ultra FineLine BGA package.

Table 15–15. 484-Pin Ultra FineLine BGA Package Information

Description	Specification
Ordering Code Reference	U
Package Acronym	UBGA
Substrate Material	BT
Solder Ball Composition	Regular: 63Sn:37Pb (Typ.) Pb-free: Sn:3Ag:0.5Cu (Typ.)
JEDEC Outline Reference	MO-216 Variation: BAP-2
Maximum Lead Coplanarity	0.005 inches (0.12mm)
Weight	1.8 g
Moisture Sensitivity Level	Printed on moisture barrier bag

Table 15–16. 484-Pin Ultra FineLine BGA Package Outline Dimensions

Symbol	Millimeter		
	Min.	Nom.	Max.
A	–	–	2.20
A1	0.20	–	–
A2	0.65	–	–
A3	0.80 TYP		
D	19.00 BSC		
E	19.00 BSC		
b	0.40	0.50	0.60
e	0.80 BSC		